### 3.2x1.6mm SMD CHIP LED LAMP

Part Number: KPTL-3216SURCK Hyper Red

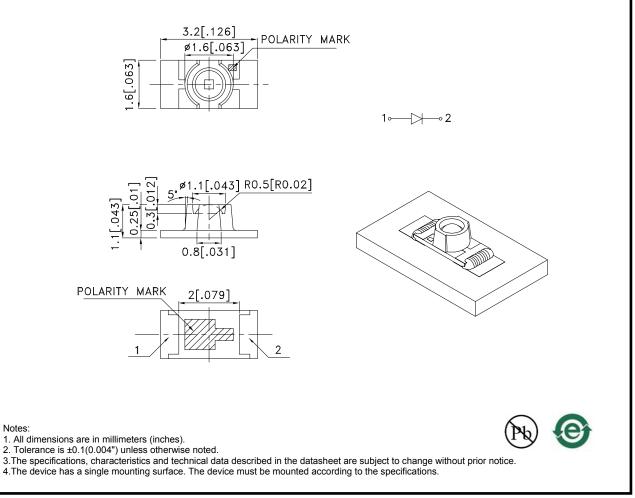
#### Features

- 3.2mmx1.6mm SMT LED, 1.1mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

#### Description

The Hyper Red source color devices are made with Al-GalnP on GaAs substrate Light Emitting Diode.

#### Package Dimensions



REV NO: V.8 CHECKED: Allen Liu DATE: APR/30/2010 DRAWN: SHANW PAGE: 1 OF 5 ERP: 1203004401

### Selection Guide

Selection Guide					
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KPTL-3216SURCK	Hyper Red (AlGaInP)	WATER CLEAR	280	550	70°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Hyper Red	650		nm	I⊧=20mA	
λD [1]	Dominant Wavelength	Hyper Red	630		nm	I⊧=20mA	
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA	
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA	
lr	Reverse Current	Hyper Red		10	uA	VR=5V	

Notes:

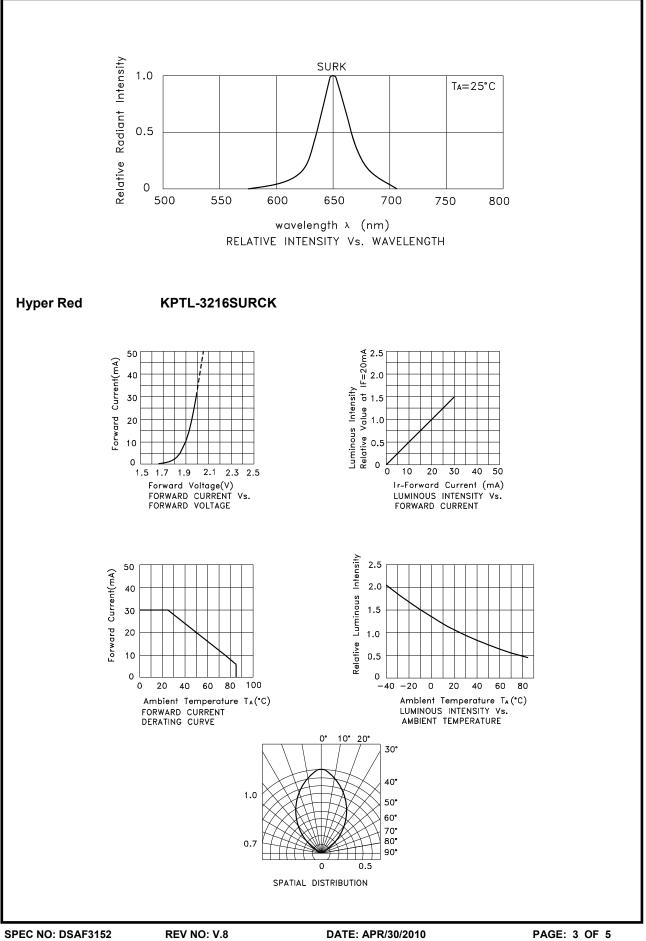
1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	185	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

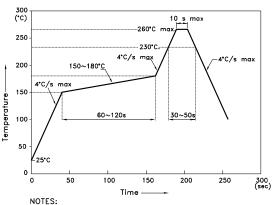
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



### **KPTL-3216SURCK**

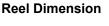
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

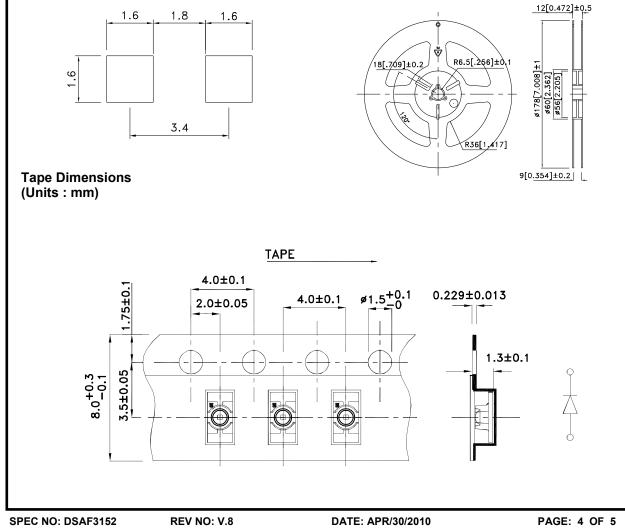
Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.







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